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## » Key

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

## Select Article Information

- ☐ 1. **Embedded test and measurement critical for deep submicron technology**  
Agarwal, V.K.;  
Test Symposium, 1997. (ATS '97) Proceedings., Sixth Asian  
17-19 Nov. 1997 Page(s):2  
Digital Object Identifier 10.1109/ATS.1997.643905  
[AbstractPlus](#) | Full Text: [PDF](#)(60 KB) IEEE CNF
- ☐ 2. **Optimizing SoC manufacturability**  
Zorian, Y.;  
VLSI Design, 2005. 18th International Conference on  
2005 Page(s):37 - 38  
Digital Object Identifier 10.1109/ICVD.2005.133  
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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(external adj (defect cause)) and ((void\$4 omit\$4 skip\$4) with (repair fix resolve))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:31
L8	29166	("707").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 08:44
L10	151	L8 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:08
L11	28	L8 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and repair	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:52
L12	3	L8 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:09
L15	2	us-20050175231-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 09:56
L16	24	((detect\$3 with (fault defect failure) with (product workpiece device component)) same (external adj (fault defect failure))) and (database storage memory)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:12
L19	57	(detect\$3 with (fault defect failure) with (product workpiece device component)) same (external adj (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:18
L20	117	(test\$3 with (device product workpiece) with external with defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:18

L21	30	(test\$3 with (device product workpiece) with external with defect) and repair	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:19
L22	8	(test\$3 with (device product workpiece) with external with defect).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:22
L23	23	(test\$3 with (device product workpiece) with external with defect).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:07
L24	4	(test\$3 same (device product workpiece) same (external adj defect)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:23
L25	1	(test\$3 same (device product workpiece) same (external adj defect) same repair).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:23
L29	731	"365".clas. and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:10
L30	64	L29 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:10
L31	311	"379".clas. and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:10
L32	5	L31 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:10

L33	189	"705".clas. and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:10
L34	3	L33 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:11
L35	151	"707".clas. and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:11
L36	3	L35 and (detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:18
L37	875	(detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and ((external surface outside) with (fault defect failure)) and (repair with (fault defective malfunction defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:20
L39	202	(detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and (external with (fault defective malfunction defect failure) with (product workpiece device component)) and (repair with (fault defective malfunction defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:22

L40	4	(detect\$3 test\$4) and (product workpiece device component) and (fault defect failure) and (external with (fault defective malfunction defect failure) with (product workpiece device component)) and ((skip\$4 omit\$4 ovoid\$4 don\$t) with (replace replacing repair\$3 change) with (fault defective malfunction defect failure) with (product workpiece device component))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:27
L41	8	(detect\$3 test\$4) same (product workpiece device component) same (fault defective malfunction defect failure) same (external with (fault defective malfunction defect failure)) same (skip skipping omit omitting avoid avoiding don\$t) same (replace replacing repair repaired repairing change)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:31
S1	1	zetko\$white-tracy\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 18:01
S2	1264	qualcomm adj incorporated\$.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 10:32
S3	3	qualcomm adj incorporated\$.as. and test and defect and product	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:20
S5	3143	(apply\$3 same test same product)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:20
S6	25	(apply\$3 same test same product) and (test same indicat\$3 same defect same product)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:22
S7	3	(apply\$3 same test same product) and (test same indicat\$3 same defect same product) and (defect same external same product)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:21

S11	1658	(test with product) and (test same defect same product)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:23
S12	3	(test with product) and (test same defect same product) and (skip\$4 same repair same product same defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 12:39
S13	3	(test with (workpiece wafer lot product)) and (test same defect same (workpiece wafer lot product)) and (skip\$4 same repair same (workpiece wafer lot product) same defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 12:41
S14	85	((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) with (workpiece wafer lot product)) and ((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) same (defect fault fail\$3 flaw deficiency) same (workpiece wafer lot product)) and ((skip\$4 omit\$4 void\$3 exclud\$3 avoid) same (repair\$3 fix\$3 mend\$3 rstor\$3) same (workpiece wafer lot product) same (defect fault fail\$3 flaw deficiency))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 12:49
S15	40	((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) with (workpiece wafer lot product)) same ((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) same (defect fault fail\$3 flaw deficiency) same (workpiece wafer lot product)) same ((skip\$4 omit\$4 void\$3 exclud\$3 avoid) same (repair\$3 fix\$3 mend\$3 rstor\$3) same (workpiece wafer lot product) same (defect fault fail\$3 flaw deficiency))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:58

S16	5	((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) with (workpiece wafer lot product)) same ((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) same (defect fault fail\$3 flaw deficiency) same (workpiece wafer lot product)) same ((skip\$4 omit\$4 void\$3 exclud\$3 avoid) same (repair\$3 fix\$3 mend\$3 rstor\$3) same (workpiece wafer lot product) same (defect fault fail\$3 flaw deficiency))) and database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:47
S21	7	((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) with (workpiece wafer lot product)) same ((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) same (defect fault fail\$3 flaw deficiency) same (workpiece wafer lot product)) same ((skip\$4 omit\$4 void\$3 exclud\$3 avoid) same (repair\$3 fix\$3 mend\$3 rstor\$3) same (workpiece wafer lot product) same (defect fault fail\$3 flaw deficiency)) and (database file list record storage memory) and process\$3 and input and output and bus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:00
S22	5	((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) with (workpiece wafer lot product)) same ((test\$3 examin\$4 experiment\$3 check\$3 analysis analyz\$3 assess\$3) same (defect fault fail\$3 flaw deficiency) same (workpiece wafer lot product)) same ((skip\$4 omit\$4 void\$3 exclud\$3 avoid) same (repair\$3 fix\$3 mend\$3 rstor\$3) same (workpiece wafer lot product) same (defect fault fail\$3 flaw deficiency)) and (database file list record storage memory) and process\$3 and input and output and bus not S16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:39
S32	113	((test\$3 with (workpiece device dut product)) same (failure defect fail error fault deficiency) same (repair fix restore mend)) and (quality with (assurance control))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:42

S34	90	((test\$3 with (workpiece device dut product)) same (failure defect fail error fault deficiency) same (repair fix restore mend)) and (quality with (assurance control)) and (database storage memory) and process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 16:16
S35	54	((test\$3 with (workpiece device dut product)) same (failure defect fail error fault deficiency) same (repair fix restore mend)) and (quality with (assurance control)) and (database storage memory) and process\$3 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 16:17
S36	48	("6292830" "5778368" "6130959" "5394509" "6125353" "6287765" "6760722" "5665953" "5828825" "5226316" "5438262" "5500823" "5550468" "5638331" "5768290" "5994886" "6023433" "6751343" "6009422" "4931929" "4970681" "5404507" "5457738" "5594898" "5596712" "5715444" "5794230" "5870771" "5895463" "5897639" "5909023" "5923327" "5983219" "6023683" "6032145" "6055516" "6078892" "6084951" "6088629" "6098065" "6151643" "6169992" "6173279" "6185576" "6188851" "6199059" "6226367" "6226640" "6226367" "6226640").pn.	US-PGPUB; USPAT	OR	ON	2005/09/13 14:40
S48	3	(wafer with yield) and defect and (external adj defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:35
S50	45	(wafer with yield) and defect and (isolate\$3 adj defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:35
S52	12	defect and (isolate\$3 adj defect) and ((skipping skip omit\$4 void\$3 avoid\$3) with repair)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:09
S53	594	(detect detecting detection) with external with defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:10



S54	3	((detect detecting detection) with external with defect) same repair	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:10
S57	118	(defect with classification) and (external with defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:41
S58	11	(defect with classification) and (external with defect) and repair	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:46
S59	773	(external with defect) and repair	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:46
S61	3	(external with defect) and (skip same repair)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:51
S62	948	(detect\$3 with (fault defect failure) with (product workpiece device component)) same (external with (fault defect failure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:53
S67	5	((detect\$3 with (fault defect failure) with (product workpiece device component)) same (external adj (fault defect failure))) and (database storage memory) and search\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:45
S69	6	(test with case with database) and (defect with tracking with database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 08:29